

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3672079

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WEI CHEN	12/21/2015
RUNMING GUO	12/21/2015
RECEIVING PARTY DATA	
Name:	GD MIDEA ENVIRONMENT APPLIANCES MFG CO., LTD.
Street Address:	NO. 28 EAST DISTRICT HESUI INDUSTRIAL PARK, DONGFU ROAD
Internal Address:	DONGFENG
City:	ZHONGSHAN
State/Country:	CHINA
Postal Code:	528425
Name:	MIDEA GROUP CO., LTD.
Street Address:	B26-28F, MIDEA HEADQUARTER BUILDING, NO. 6 MIDEA AVENUE
Internal Address:	BEIJIAO, SHUNDE
City:	FOSHAN
State/Country:	CHINA
Postal Code:	528311
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29548531
CORRESPONDENCE DATA	
Fax Number:	(716)819-4787
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	716-856-4000
Email:	ipdocketing@hodgsonruss.com
Correspondent Name:	HODGSON RUSS LLP THE GUARANTY BUILDING
Address Line 1:	140 PEARL STREET
Address Line 2:	SUITE 100
Address Line 4:	BUFFALO, NEW YORK 14202-4040
ATTORNEY DOCKET NUMBER:	PDOM1153456US

NAME OF SUBMITTER:	SAMUEL E. KIELAR
SIGNATURE:	/samuel e kielar/
DATE SIGNED:	12/28/2015
Total Attachments: 1 source=PDOM1153456US-Assignment#page1.tif	

ASSIGNMENT OF INVENTION

WHEREAS, I, **CHEN, Wei**, No. 28 East District Hesui Industrial Park, Dongfu Road, Dongfeng, Zhongshan, Guangdong 528425, China; and **GUO, Runming**, No. 28 East District Hesui Industrial Park, Dongfu Road, Dongfeng, Zhongshan, Guangdong 528425, China, have invented certain new and ornamental improvements in a **FAN**, for which a design patent application for Letters Patent in the United States was filed on December 15, 2015 and assigned U.S. Appl. No. 29/548,531, claiming priority to Chinese patent application No. 201530380713.0 filed on September 29, 2015.

AND WHEREAS, **JIANGSU MIDEA CLEANING APPLIANCES CO., LTD.**, No. 39 Caohu Avenue, Xiangcheng Economic Development Zone, Suzhou, Jiangsu 215100, China; and **MIDEA GROUP CO., LTD.**, B26-28F, Midea Headquarter Building, No. 6 Midea Avenue, Beijiao, Shunde, Foshan, Guangdong 528311, P. R. China (collectively, the "ASSIGNEES"), is desirous of acquiring all interest in said invention, said application, and in any Letters Patent which may be granted therefor.


AND WHEREAS, at the time the improvements were made, I was under an obligation to assign all of my right, title, and interest in said improvements to the ASSIGNEES.

NOW THIS INDENTURE WITNESSETH, that for the sum of one dollar and other valuable consideration to me in hand paid, the receipt of which is hereby acknowledged, I hereby assign, sell, and transfer unto the ASSIGNEES my entire right, title, and interest in said improvements, said application, and all national phase, divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to any and all priority rights, rights under the International Convention For The Protection Of Industrial Property, rights under the Patent Cooperation Treaty, and other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto.

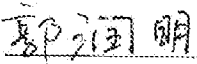
And I hereby authorize and request the Commissioner of Patents and Trademarks to issue said United States Letters Patent to said ASSIGNEES as the assignees of my whole right, title, and interest thereto.

And I further agree to sign and properly execute such necessary and lawful papers for application for patents, for filing subdivisions of said application for patent, and for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid improvements, as the assignees thereof shall hereafter require and prepare at its own expense.

WITNESS, my signature and date of execution:


CHEN, Wei

2015.12.21
Date


GUO, Runming

2015.12.21
Date